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## SUBSTITUTE AMENDMENT AND RESPONSE TO OFFICE ACTION

**TO:** COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

**FROM:** Tung & Associates  
838 West Long Lake Road - Suite 120  
Bloomfield Hills, MI 48302

**DATE:** 27 January 2003

**REF:** APPLICANT : Liang  
SERIAL NO. : 09/885,784  
ART UNIT : 2823  
FILING DATE : 20 June 2001  
ATT'Y NO. : 67,200-327; TSMC 00-132  
EXAMINER : Julio J. Maldonado  
TITLE : Laminating Method for Forming Integrated Circuit  
Microelectronic Fabrication

#10  
Amend #10  
Osmalski Logan  
2/25/03

In response to an office communication mailed on 21 January 2003, please

consider the following amendments and remarks pertaining to the above referenced application.

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on January 30, 2003.

  
Kathy Dixon